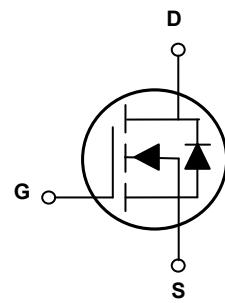
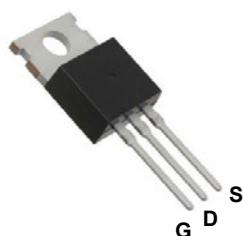


Main Product Characteristics

$V_{(BR)DSS}$	600V
$R_{DS(ON)}$	0.57Ω (Max.)
I_D	7A



TO-220

Schematic Diagram

Features and Benefits

- Optimized the cell structure
- Low on-resistance and low gate charge
- Featuring low switching and drive losses
- Fast switching and reverse body recovery
- High ruggedness and robustness



Description

The GSFH60R570 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V_{DS}	600	V
Gate-Source Voltage	V_{GS}	± 30	V
Drain Current-Continuous, at Steady-State, ($T_C=25^\circ\text{C}$)	I_D	7	A
Drain Current-Continuous, at Steady-State, ($T_C=100^\circ\text{C}$)		4.4	
Drain Current-Pulsed	I_{DM}	28	A
Single Pulse Avalanche Energy ¹	E_{AS}	221	mJ
Power Dissipation ($T_C=25^\circ\text{C}$)	P_D	60	W
		0.48	W/ $^\circ\text{C}$
Body Diode Reverse Voltage Slope ²	dv/dt	50	V/ns
MOS dv/dt Ruggedness ³	dv/dt	100	V/ns
Junction-to-Ambient (PCB Mounted, Steady-State)	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.08	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	T_J	-55 To +150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 To +150	$^\circ\text{C}$

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	600	-	-	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=600\text{V}, V_{\text{GS}}=0\text{V}$	-	-	200	nA
Gate-Source Forward Current	I_{GSS}	$V_{\text{GS}}=\pm 30\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=3.5\text{A}, T_J=25^\circ\text{C}$	-	0.47	0.57	Ω
		$V_{\text{GS}}=10\text{V}, I_{\text{D}}=3.5\text{A}, T_J=125^\circ\text{C}$	-	0.95	-	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	2.0	-	4.0	V
Dynamic and Switching Characteristics						
Total Gate Charge ^{4,5}	Q_g	$V_{\text{DD}}=480\text{V}, I_{\text{D}}=7\text{A}, V_{\text{GS}}=10\text{V}$	-	19	-	nC
Gate-Source Charge ^{4,5}	Q_{gs}		-	5.1	-	
Gate-Drain ("Miller") Charge ^{4,5}	Q_{gd}		-	8.6	-	
Turn-On Delay Time ^{4,5}	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=300\text{V}, R_{\text{G}}=25\Omega, V_{\text{GS}}=10\text{V}, I_{\text{D}}=7\text{A}$	-	20	-	nS
Rise Time ^{4,5}	t_r		-	40	-	
Turn-Off Delay Time ^{4,5}	$t_{\text{d}(\text{off})}$		-	91	-	
Fall Time ^{4,5}	t_f		-	38	-	
Input Capacitance	C_{iss}	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	602	-	pF
Output Capacitance	C_{oss}		-	25	-	
Reverse Transfer Capacitance	C_{rss}		-	0.8	-	
Gate Resistance	R_g	$F=1\text{MHz}$	-	4.7	-	Ω
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current (Body Diode)	I_s	$T_C=25^\circ\text{C}$, MOSFET symbol showing the integral reverse p-n junction diod	-	-	7	A
Pulsed Source Current	I_{SM}		-	-	28	A
Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_s=7\text{A}$	-	-	1.4	V
Reverse Recovery Time ³	t_{rr}	$V_{\text{GS}}=0\text{V}, I_F=7\text{A}, d_{\text{IF}}/dt=100\text{A}/\mu\text{s}$	-	240	-	nS
Reverse Recovery Charge ³	Q_{rr}		-	2.4	-	μC

Note:

1. $L=79\text{mH}, I_{\text{AS}}=2.2\text{A}, V_{\text{DD}}=100\text{V}$, starting temperature $T_J=25^\circ\text{C}$.
2. $V_{\text{DS}}=0-400\text{V}, I_{\text{SD}}<20\text{A}, T_J=25^\circ\text{C}$.
3. $V_{\text{DS}}=0-480\text{V}$.
4. Pulse test : pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
5. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

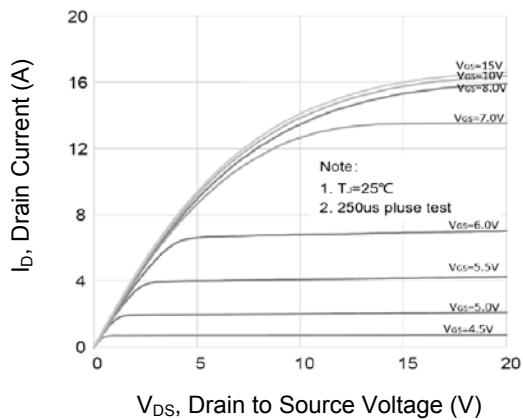


Figure 1. Output Characteristics

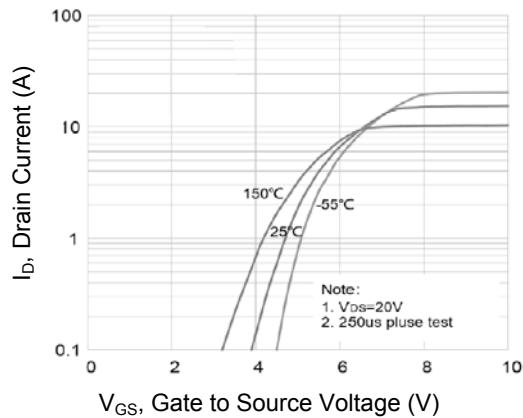


Figure 2. Transfer Characteristics

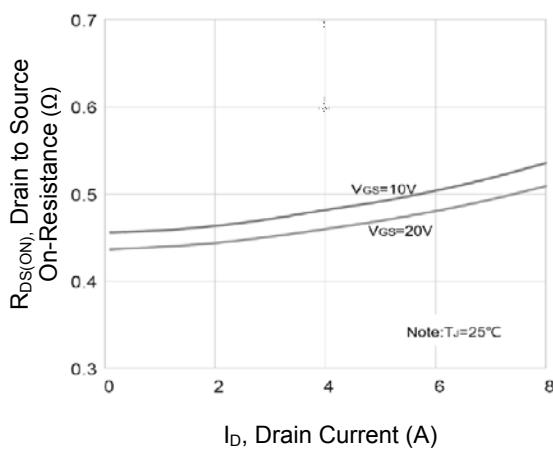


Figure 3. $R_{DS(ON)}$ vs. Drain Current

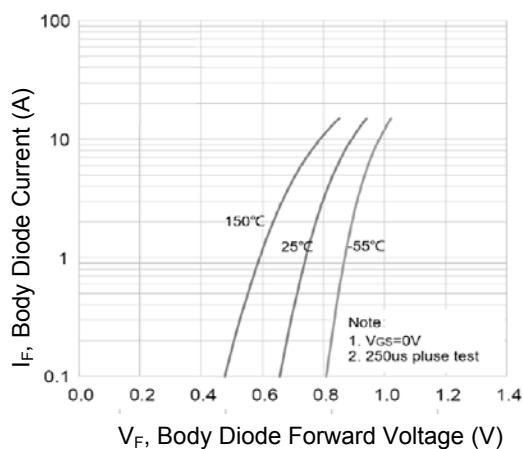


Figure 4. Body Diode Characteristics

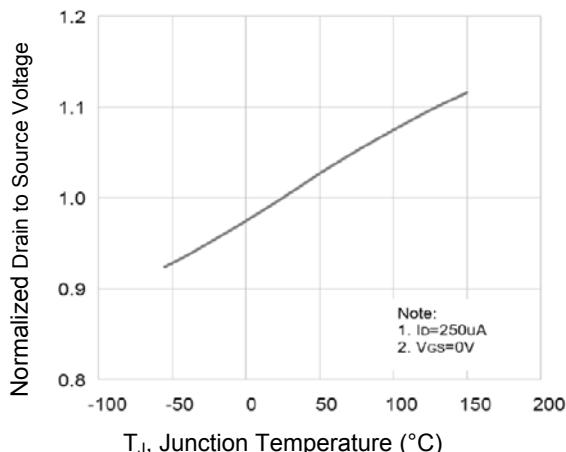


Figure 5. Normalized BV_{DSS} vs. T_J

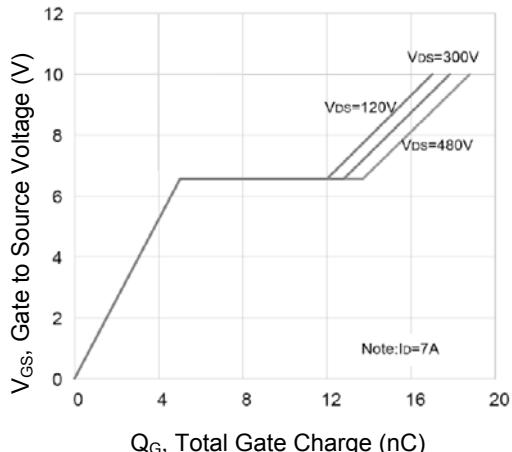


Figure 6. Gate Charge

Typical Electrical and Thermal Characteristic Curves

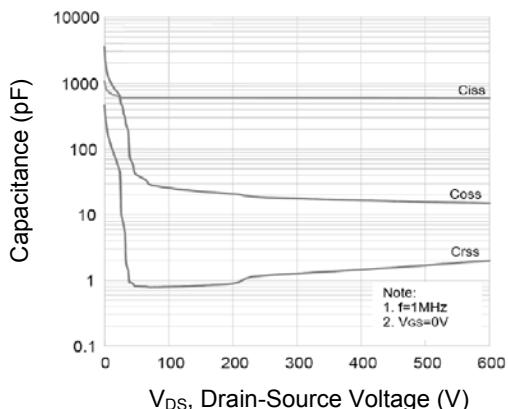


Figure 7. Capacitance Characteristics

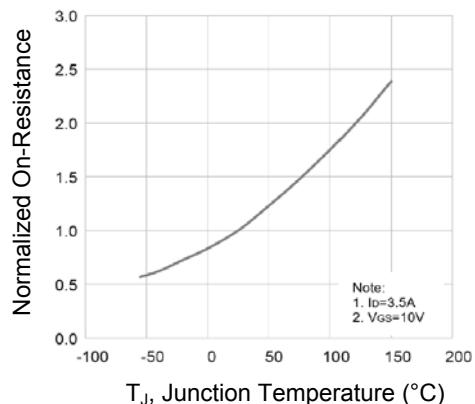


Figure 8. Normalized $R_{DS(ON)}$ vs. T_J

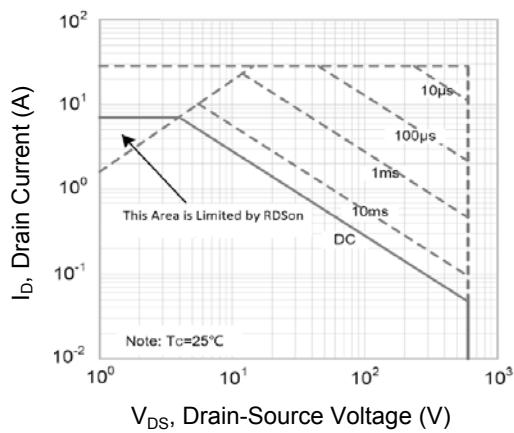
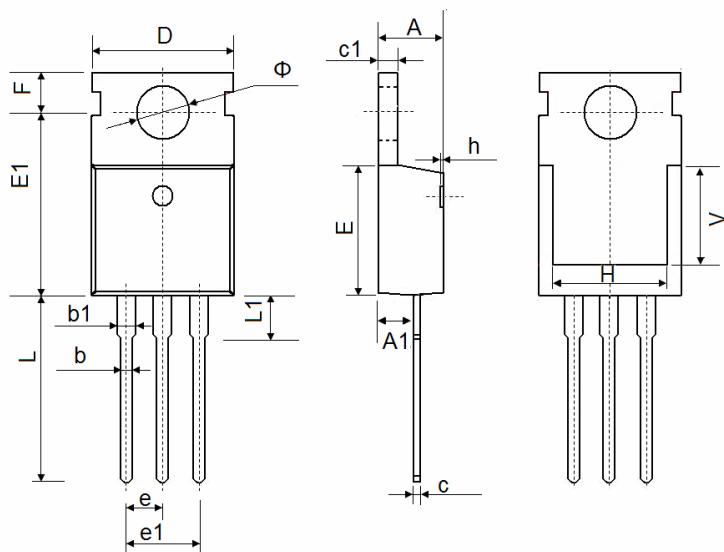


Figure 9. Safe Operation Area

Package Outline Dimensions (TO-220)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.950	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP		0.100 TYP	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	6.900 REF		0.276 REF	
Φ	3.400	3.800	0.134	0.150